LNP™ THERMOCOMP™ Compound NX11302
Asia Pacific: COMMERCIAL

This is a PC/ABS compound with colorable, good plating, surface and mechanical performance, a good candidate for Laser Direct Structuring applications

TYPICAL PROPERTIES[1]	TYPICAL VALUE	Unit	Standard
MECHANICAL			
Tensile Stress, yld, Type I, 50 mm/min	470	kgf/cm²	ASTM D 638
Tensile Stress, brk, Type I, 50 mm/min	460	kgf/cm²	ASTM D 638
Tensile Strain, yld, Type I, 50 mm/min	4.6	%	ASTM D 638
Tensile Strain, brk, Type I, 50 mm/min	75	%	ASTM D 638
Tensile Modulus, 50 mm/min	23900	kgf/cm²	ASTM D 638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	800	kgf/cm²	ASTM D 790
Flexural Stress, brk, 1.3 mm/min, 50 mm span	790	kgf/cm²	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	22700	kgf/cm²	ASTM D 790
IMPACT			
Izod Impact, notched, 23°C	56	cm-kgf/cm	ASTM D 256
THERMAL			
HDT, 1.82 MPa, 3.2mm, unannealed	106	°C	ASTM D 648
CTE, -40°C to 40°C, flow	7.1E-05	1/°C	ASTM E 831
CTE, -40°C to 40°C, xflow	7.6E-05	1/°C	ASTM E 831
PHYSICAL			
Density	1.22	g/cm³	ASTM D 792
Water Absorption, 24 hours	0.01	%	ASTM D 570
Moisture Absorption, 50% RH, 24 hrs	0.01	%	ASTM D 570
Mold Shrinkage, flow, 24 hrs (5)	0.6	%	ASTM D 955
Mold Shrinkage, xflow, 24 hrs (5)	0.6	%	ASTM D 955
Melt Volume Rate, MVR at 260°C/5.0 kg	14	cm³/10 min	ISO 1133
ELECTRICAL			
Relative Permittivity, 1 GHz	2.94	-	IEC 60250
Dissipation Factor, 1 GHz	0.0057	-	IEC 60250

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PROCESSING PARAMETERS	TYPICAL VALUE	Unit
Injection Molding		
Drying Temperature	85 - 95	°C
Drying Time	2 - 4	hrs
Drying Time (Cumulative)	8	hrs
Maximum Moisture Content	0.01	%
Melt Temperature	220 - 260	°C
Nozzle Temperature	220 - 260	°C
Front - Zone 3 Temperature	215 - 255	°C
Middle - Zone 2 Temperature	215 - 255	°C
Rear - Zone 1 Temperature	200 - 250	°C
Mold Temperature	40 - 75	°C
Back Pressure	0.5 - 0.9	MPa
Screw Speed	50 - 100	rpm
Shot to Cylinder Size	50 - 70	%
Vent Depth	0.038 - 0.051	mm